

# MOS FIELD EFFECT TRANSISTOR NP80N03MDE, NP80N03NDE

## SWITCHING N-CHANNEL POWER MOS FET

### DESCRIPTION

These products are N-channel MOS Field Effect Transistors designed for high current switching applications.

### ORDERING INFORMATION

PART NUMBER	LEAD PLATING	PACKING	PACKAGE
NP80N03MDE-S18-AY <sup>Note</sup>	Pure Sn (Tin)	Tube 50 p/tube	TO-220 (MP-25K) typ. 1.9 g
NP80N03NDE-S18-AY <sup>Note</sup>	Pure Sn (Tin)	Tube 50 p/tube	TO-262 (MP-25SK) typ. 1.8 g

**Note** Under development

### FEATURES

- Channel Temperature 175 degree rated
- Super Low On-state Resistance  
 $R_{DS(on)1} = 7.0 \text{ m}\Omega \text{ MAX. (} V_{GS} = 10 \text{ V, } I_D = 40 \text{ A)}$   
 $R_{DS(on)2} = 9.0 \text{ m}\Omega \text{ MAX. (} V_{GS} = 5 \text{ V, } I_D = 40 \text{ A)}$   
 $R_{DS(on)3} = 11 \text{ m}\Omega \text{ MAX. (} V_{GS} = 4.5 \text{ V, } I_D = 40 \text{ A)}$
- Low  $C_{iss}$  :  $C_{iss} = 2600 \text{ pF TYP.}$

### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

Drain to Source Voltage (V <sub>GS</sub> = 0 V)	V <sub>DSS</sub>	30	V
Gate to Source Voltage (V <sub>DS</sub> = 0 V)	V <sub>GSS</sub>	±20	V
Drain Current (DC) (T <sub>C</sub> = 25°C) <sup>Note1</sup>	I <sub>D(DC)</sub>	±80	A
Drain Current (pulse) <sup>Note2</sup>	I <sub>D(pulse)</sub>	±320	A
Total Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>T1</sub>	120	W
Total Power Dissipation (T <sub>A</sub> = 25°C)	P <sub>T2</sub>	1.8	W
Channel Temperature	T <sub>ch</sub>	175	°C
Storage Temperature	T <sub>stg</sub>	-55 to +175	°C
Single Avalanche Current <sup>Note3</sup>	I <sub>AS</sub>	50/40/9	A
Single Avalanche Energy <sup>Note3</sup>	E <sub>AS</sub>	2.5/160/400	mJ

**Notes** 1. Calculated constant current according to MAX. Allowable channel temperature.

2.  $PW \leq 10 \mu\text{s}$ , Duty cycle  $\leq 1\%$

3. Starting T<sub>ch</sub> = 25°C, R<sub>G</sub> = 25 Ω, V<sub>GS</sub> = 20 → 0 V (See Figure 4.)

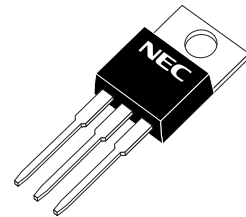
### THERMAL RESISTANCE

Channel to Case Thermal Resistance	R <sub>th(ch-C)</sub>	1.25	°C/W
Channel to Ambient Thermal Resistance	R <sub>th(ch-A)</sub>	83.3	°C/W

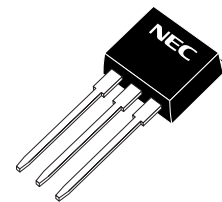
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(TO-220)



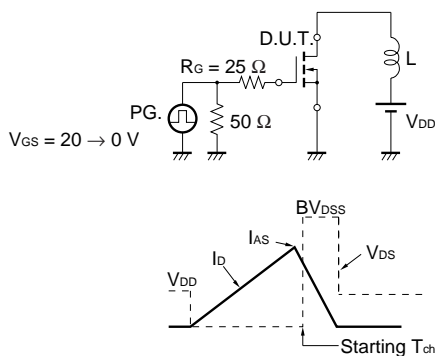
(TO-262)



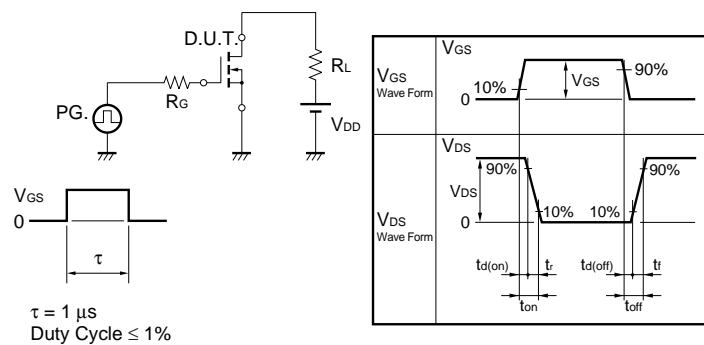
**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)**

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	I <sub>bss</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			10	μA
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V			±100	nA
Gate to Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.5	2.0	2.5	V
Forward Transfer Admittance	y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 40 A	20	41		S
Drain to Source On-state Resistance	R <sub>DS(on)1</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 40 A		5.3	7.0	mΩ
	R <sub>DS(on)2</sub>	V <sub>GS</sub> = 5 V, I <sub>D</sub> = 40 A		6.8	9.0	mΩ
	R <sub>DS(on)3</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 40 A		7.5	11	mΩ
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25 V		2600	3900	μF
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V		590	890	pF
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1 MHz		270	490	pF
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 15 V, I <sub>D</sub> = 40 A		20	44	ns
Rise Time	t <sub>r</sub>	V <sub>GS</sub> = 10 V		12	31	ns
Turn-off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> = 1 Ω		60	120	ns
Fall Time	t <sub>f</sub>			14	35	ns
Total Gate Charge 1	Q <sub>G1</sub>	I <sub>D</sub> = 80 A, V <sub>DD</sub> = 24 V, V <sub>GS</sub> = 10 V		48	72	nC
Total Gate Charge 2	Q <sub>G2</sub>	V <sub>DD</sub> = 24 V		28	42	nC
Gate to Source Charge	Q <sub>GS</sub>	V <sub>GS</sub> = 5 V		10		nC
Gate to Drain Charge	Q <sub>GD</sub>	I <sub>D</sub> = 80 A		14		nC
Body Diode Forward Voltage	V <sub>F(S-D)</sub>	I <sub>F</sub> = 80 A, V <sub>GS</sub> = 0 V		1.0		V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 80 A, V <sub>GS</sub> = 0 V		34		ns
Reverse Recovery Charge	Q <sub>rr</sub>	di/dt = 100 A/μs		22		nC

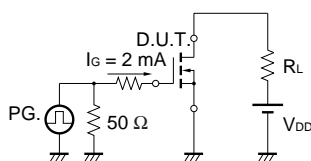
**TEST CIRCUIT 1 AVALANCHE CAPABILITY**



**TEST CIRCUIT 2 SWITCHING TIME**



**TEST CIRCUIT 3 GATE CHARGE**



TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)

Figure1. DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA

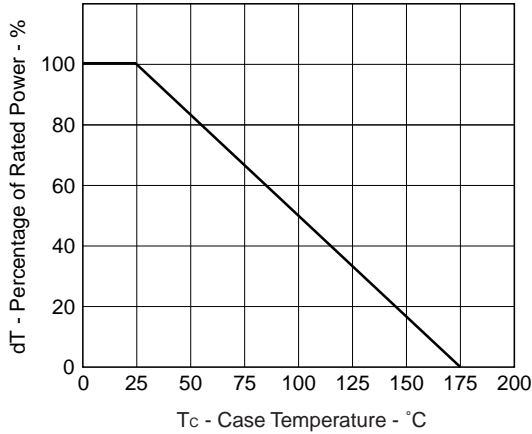


Figure2. TOTAL POWER DISSIPATION vs. CASE TEMPERATURE

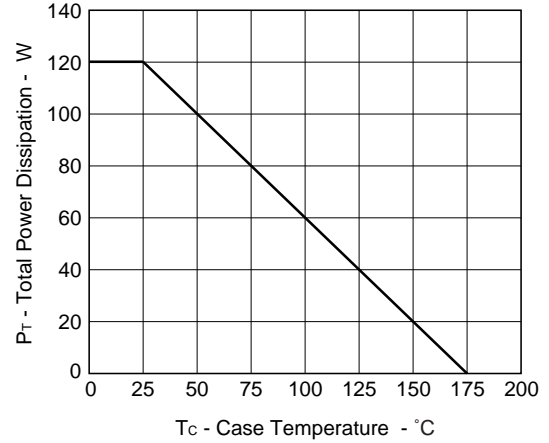


Figure3. FORWARD BIAS SAFE OPERATING AREA

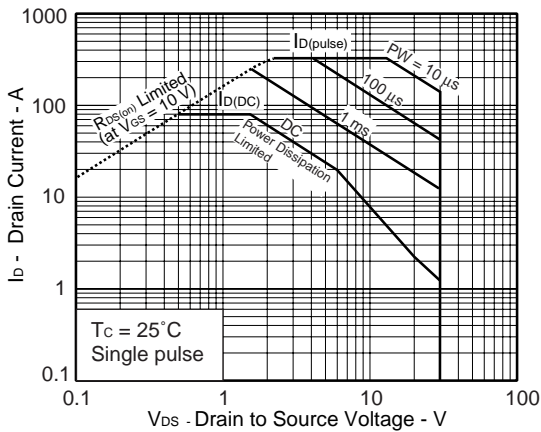


Figure4. SINGLE AVALANCHE ENERGY DERATING FACTOR

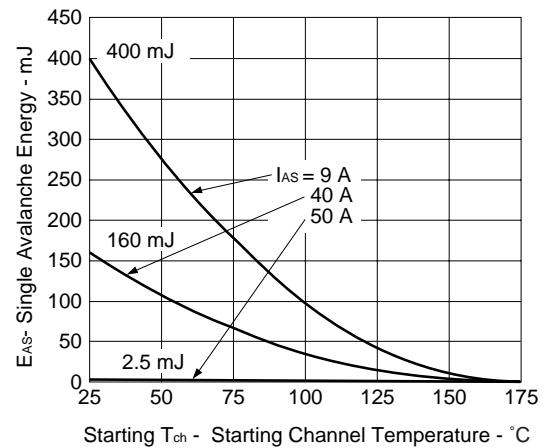


Figure5. TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

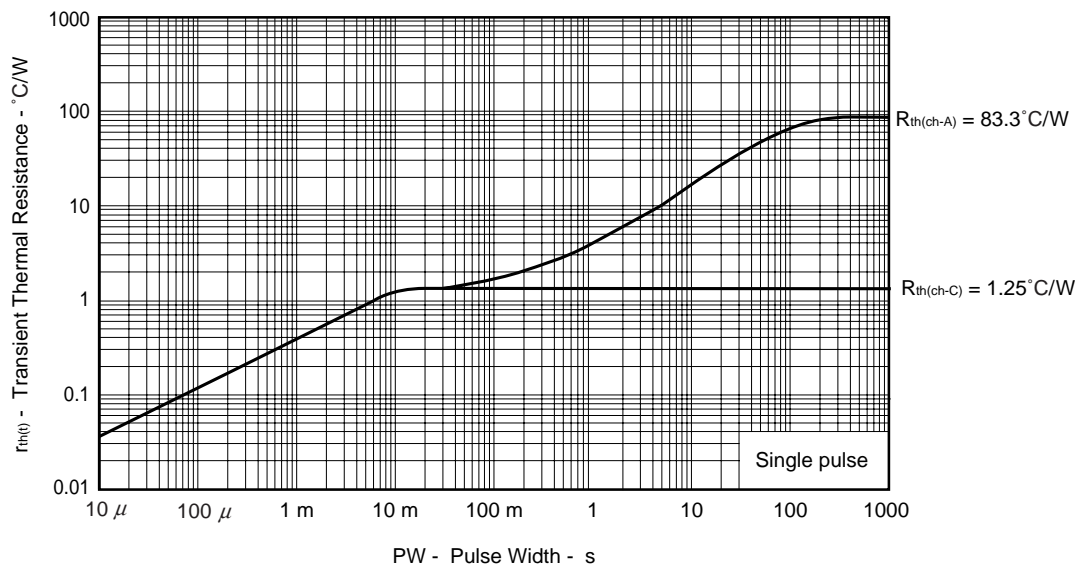


Figure6. FORWARD TRANSFER CHARACTERISTICS

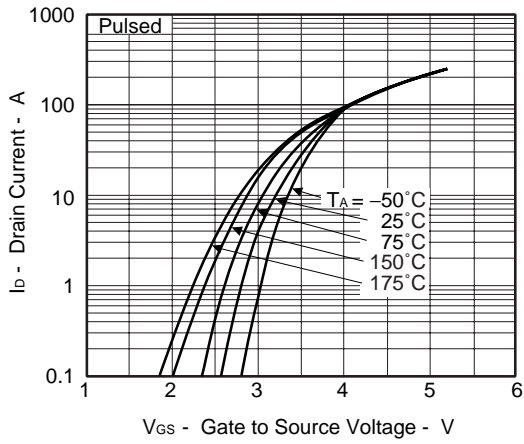


Figure7. DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE

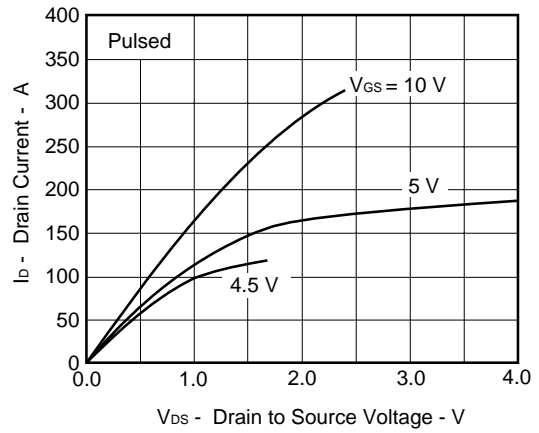


Figure8. FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

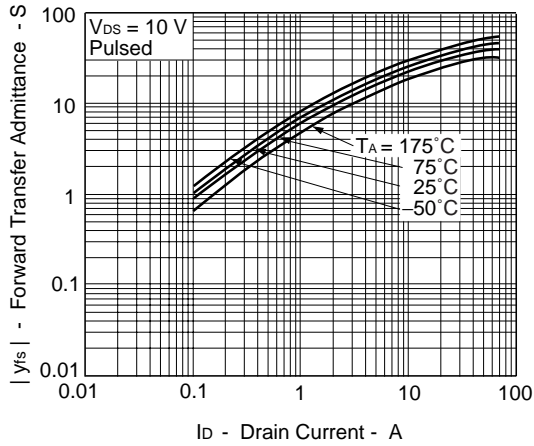


Figure9. DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

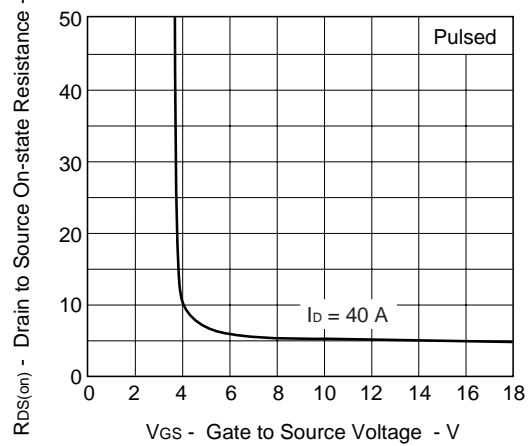


Figure10. DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

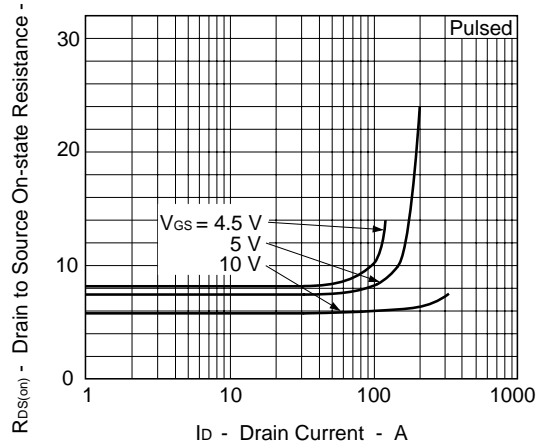


Figure11. GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE

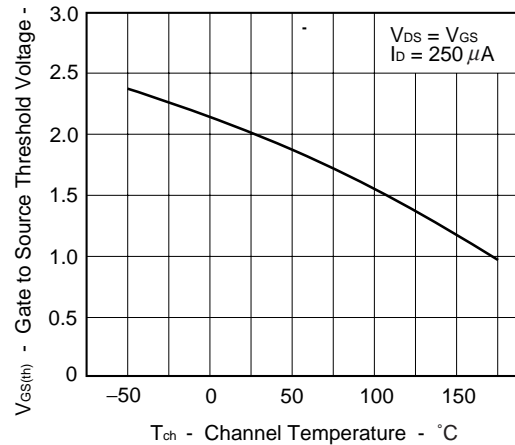


Figure12. DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE

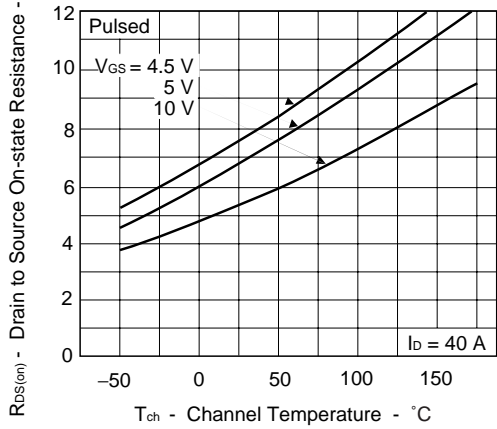


Figure13. SOURCE TO DRAIN DIODE FORWARD VOLTAGE

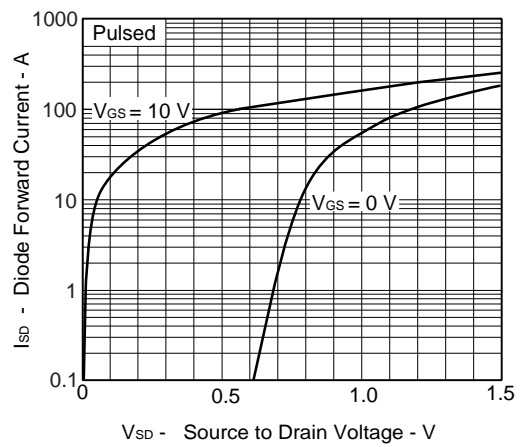


Figure14. CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

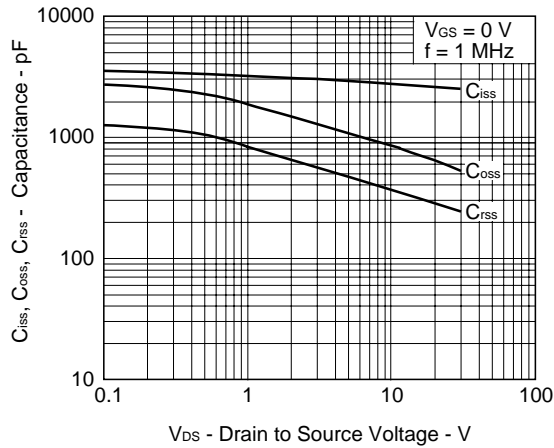


Figure15. SWITCHING CHARACTERISTICS

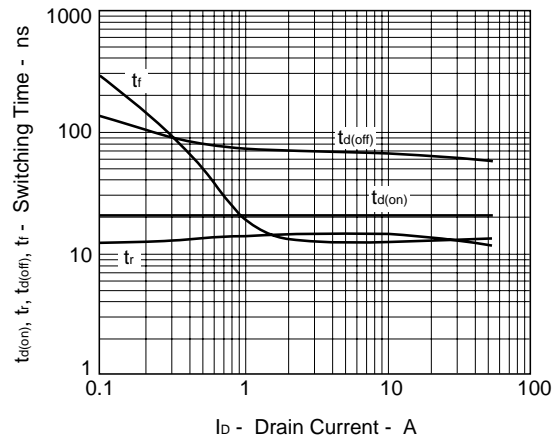


Figure16. REVERSE RECOVERY TIME vs. DRAIN CURRENT

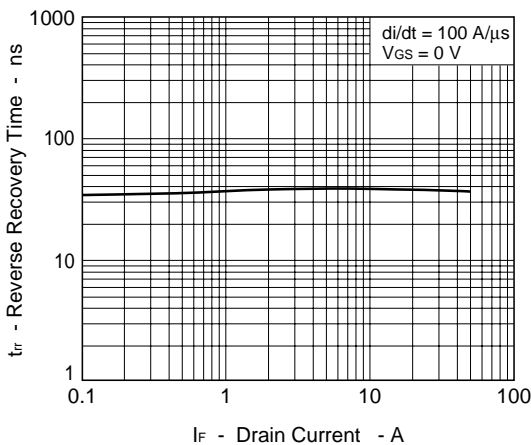
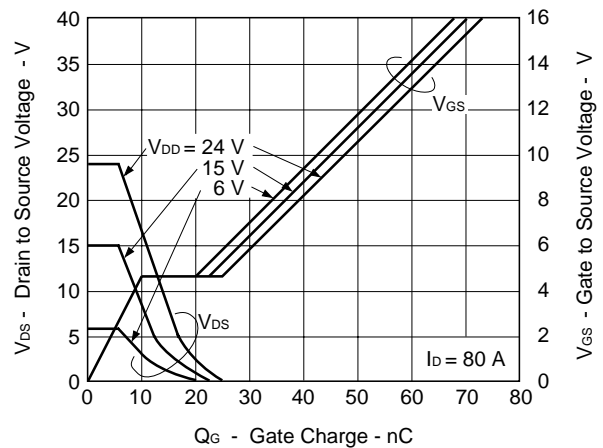
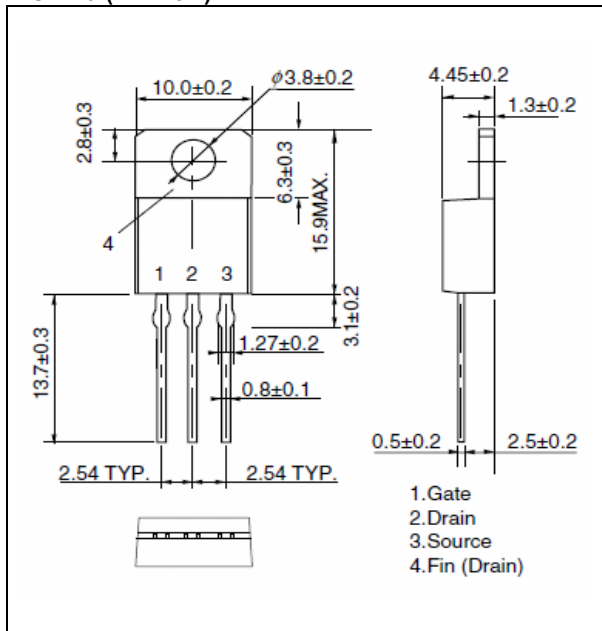


Figure17. DYNAMIC INPUT/OUTPUT CHARACTERISTICS

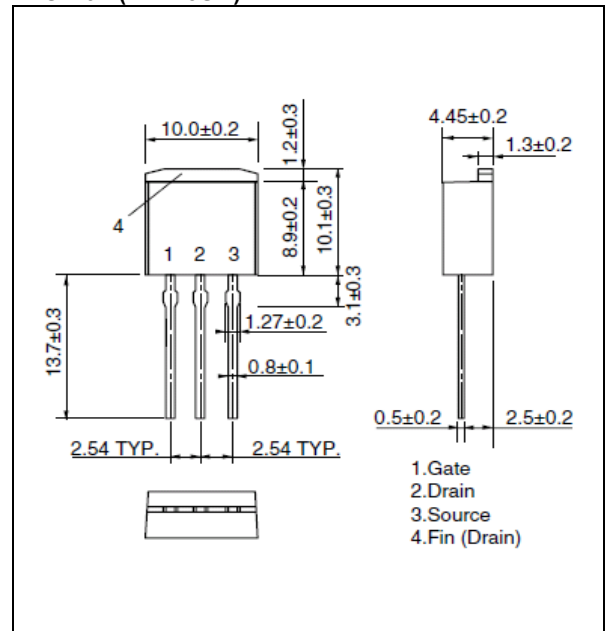


PACKAGE DRAWINGS (Unit: mm)

TO-220 (MP-25K) <sup>Note</sup>

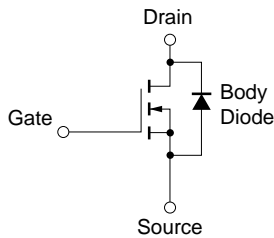


TO-262 (MP-25SK) <sup>Note</sup>



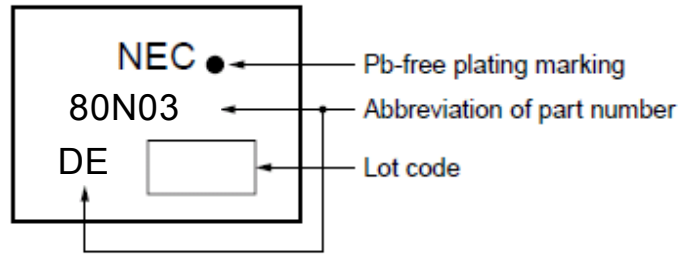
Note Under development

EQUIVALENT CIRCUIT



**Remark** Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

**MARKING INFORMATION**



**RECOMMENDED SOLDERING CONDITIONS**

These products should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, please contact an NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (<http://www.necel.com/pkg/en/mount/index.html>)

Soldering Method	Soldering Condition	Recommended Condition Symbol
Wave soldering MP-25K, MP-25SK	Maximum temperature (Solder temperature): 260°C or below Time: 10 s or less Maximum chlorine content of rosin flux: 0.2% (wt.) or less	THDWS
Partial heating MP-25K, MP-25SK	Maximum temperature (Pin temperature): 350°C or below Time (per side of the device): 3 seconds or less Maximum chlorine content of rosin flux: 0.2% (wt.) or less	P350

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